



Aerospace Grade Microwave Material with Radiation Resistance & High Performance

Excellent Dimensional Stability with Highest Degree of Phase Stability vs. Temperature

RS300 is a PTFE composite utilizing low coefficient of expansion fiberglass as the supporting material and mixing with a specially treated nanometer ceramic, which provides both excellent dimensional stability and the highest degree of phase stability, critical in multi-layer designs. RS300 is in a “League of its Own” when it is combined with thin film resistor-conductor materials such as Ohmega-Ply® and TCR® foils utilized for embedded resistors.

RS300 has “Best-in-Class” Insertion Loss (S21) and Loss Tangent (0.0010). During Development, Relong focused not only on reducing Loss Tangent, but also in reducing Conductive Losses. As a result, RS300 Insertion Loss is “Best-In-Class”.

In order to ensure the application of space harsh environment, we add special filler to ensure the radiation resistance in space without affecting the electrical properties.

The impact of copper foil roughness on conductor loss is due to increase in transmission line resistance as a result of skin effect. Relong’s RS300 was designed to provide a quality peel strength without having to resort to the utilization of the higher loss, rougher coppers prevalent in competitive products to achieve acceptable copper adhesion.

RS300 has Low CTE_{xyz} and Very Low TCER for applications that require Electrical Phase Stability and Dielectric Constant Stability well over a -40 to 150°C Operating Temperature. RS300 has excellent performance (radiation resistance, dimensional stability, dielectric constant stability vs. temperature and frequency, low absorption of moisture and processing chemicals, ease of process ability), and has a price competitive advantage.

Compared with other materials, RS300 has a higher thermal conductivity, it increased heat conduction makes further increases in power capacity.

Applications include Space and other Electronics who require a higher degree of performance such as Phase Sensitive Arrays for Radar, RF/Microwave Communications, Aircraft Collision Avoidance Systems, JTRS, etc. RS300 is also a preferred material for sensitive filter applications.

Features:

- Ceramic/PTFE Microwave Composite
- Lowest Insertion Loss in Class
- “Best-in-Class” Loss Tangent (0.0010)
- Electrical Phase Stability vs. Temperature
- High Thermal Conductivity
- Tightest Dielectric Constant (± 0.03) and Thickness Tolerance

Benefits:

- Excellent Thermal Stability of DK and Df
- Phase Stability vs. temperature
- High Degree of Dimensional Stability Required for Complex, Multi-layer Boards
- Excellent CTE in X,Y and Z Directions

Typical Applications:

- Defense Microwave/RF Applications
- Radar
- Phase Fed Array Antennas
- Microwave Feed Networks
- CNI (communication, navigation and identification) Applications
- SIGINT, Satellite & Space Electronics
- Other High Frequency and High Speed Applications

Typical Properties:

| Property | Units | Value | Test Method |
|--|-------------------|------------------------|---------------------|
| 1. Electrical Properties | | | |
| Dielectric Constant (may vary by thickness) | | | |
| @ 10 GHz | - | 2.94 | IPC TM-650 2.5.5.5 |
| Dissipation Factor | | | |
| @ 10 GHz | - | 0.0010 | IPC TM-650 2.5.5.5 |
| Temperature Coefficient of Dielectric | | | |
| TC _{εr} @ 10 GHz (-40-150°C) | ppm/°C | -9 | IPC TM-650 2.5.5.5 |
| Volume Resistivity | | | |
| C96/35/90 | M Ω -cm | 4.25 x 10 ⁸ | IPC TM-650 2.5.17.1 |
| E24/125 | M Ω -cm | 1.85 x 10 ⁸ | IPC TM-650 2.5.17.1 |
| Surface Resistivity | | | |
| C96/35/90 | M Ω | 2.49 x 10 ⁸ | IPC TM-650 2.5.17.1 |
| E24/125 | M Ω | 5.48 x 10 ⁷ | IPC TM-650 2.5.17.1 |
| Electrical Strength | Volts/mil (kV/mm) | 1000(40) | IPC TM-650 2.5.6.2 |
| Dielectric Breakdown | kV | 58 | IPC TM-650 2.5.6 |
| Arc Resistance | sec | 250 | IPC TM-650 2.5.1 |
| 2. Thermal Properties | | | |
| Decomposition Temperature (Td) | | | |
| Initial | ° C | 501 | IPC TM-650 2.4.24.6 |
| 5% | ° C | 554 | IPC TM-650 2.4.24.6 |
| T260 | min | >60 | IPC TM-650 2.4.24.1 |
| T288 | min | >60 | IPC TM-650 2.4.24.1 |
| T300 | min | >60 | IPC TM-650 2.4.24.1 |
| Thermal Expansion, CTE (x,y) 50-150° C | ppm/°C | 8.8 | IPC TM-650 2.4.41 |
| Thermal Expansion, CTE (z) 50-150° C | ppm/°C | 20 | IPC TM-650 2.4.24 |
| % z-axis Expansion (50-260°C) | % | 1.2 | IPC TM-650 2.4.24 |
| 3. Physical Properties | | | |
| Water Absorption | % | 0.02 | IPC TM-650 2.6.2.1 |
| Density, ambient 23° C | g/cm ³ | 2.02 | ASTM D792 Method A |
| Thermal Conductivity | W/mK | 0.56 | ASTM D5470 |
| Flammability | class | V-0 | UL-94 |
| NASA Outgassing, 125°C, ≤10 ⁻⁶ torr | | | |
| Total Mass Loss | % | 0.02 | NASA SP-R-0022A |
| Collected Volatiles | % | 0.00 | NASA SP-R-0022A |
| Water Vapor Recovered | % | 0.01 | NASA SP-R-0022A |
| 4. Mechanical Properties | | | |
| Peel Strength to Copper (1 oz/35) | | | |
| After Thermal Stress | lb/in (N/mm) | 8(1.4) | IPC TM-650 2.4.8 |
| At Elevated Temperatures (150°) | lb/in (N/mm) | 10(1.75) | IPC TM-650 2.4.8.2 |
| After Process Solutions | lb/in (N/mm) | 8(1.4) | IPC TM-650 2.4.8 |
| Young' s Modulus | kpsi (MPa) | 260 (1790) | IPC TM-650 2.4.18.3 |
| Flexural Strength (Machine/Cross) | kpsi (MPa) | 9.5/9.0 (66/62) | IPC TM-650 2.4.4 |
| Tensile Strength (Machine/Cross) | kpsi (MPa) | 4.0/3.4 (28/23) | IPC TM-650 2.4.18.3 |
| Compressive Modulus | kpsi (MPa) | 244 (1682) | ASTM D-3410 |
| Poisson' s Ratio | - | 0.23 | ASTM D-3039 |

Results listed above are typical properties, they are not to be used as specification limits. The above information creates no expressed or implied warranties. The properties of Relong laminates may vary depending on the design and application.

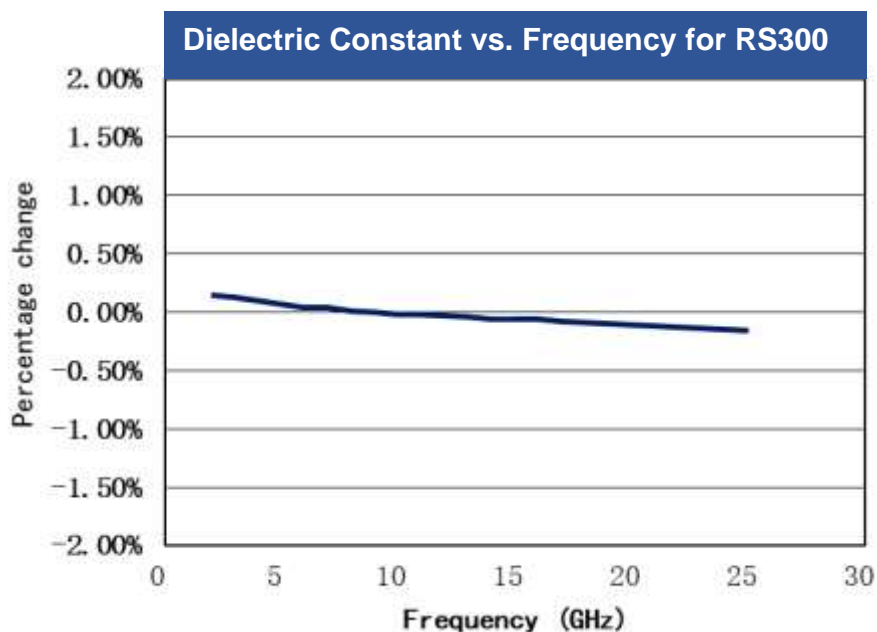


Figure 1
Demonstrates the Stability of Dielectric Constant across Frequency. This characteristic demonstrates the inherent robustness of Relong Laminates across Frequency, thus simplifying the final design process when working across EM spectrum. The stability of the Dielectric Constant of RS300 over frequency ensures easy design transition and scalability of design.

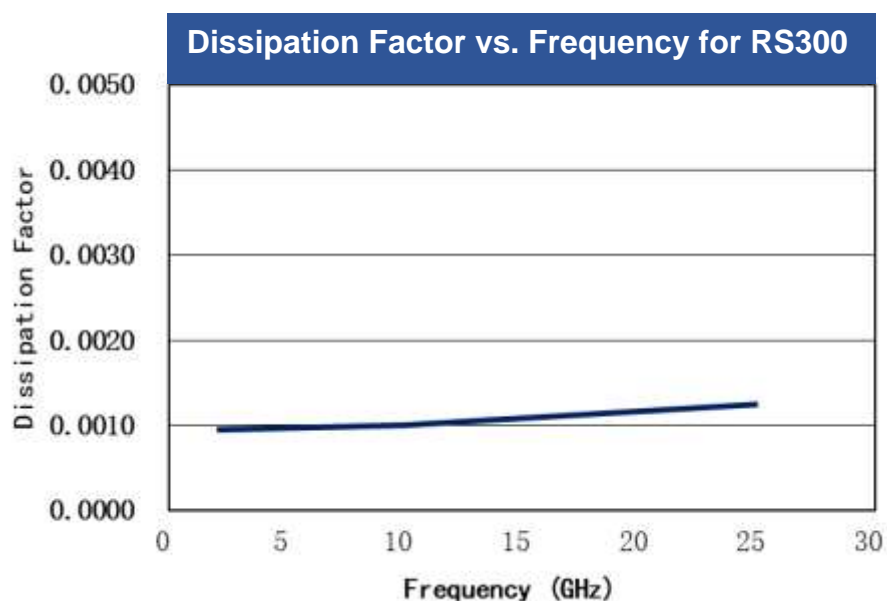


Figure 2
Demonstrates the Stability of Dissipation Factor across Frequency. This characteristic demonstrates the inherent robustness of Relong Laminates across Frequency, providing a stable platform for high frequency applications where signal integrity is critical to the overall performance of the application.

Material Availability:

RS300 laminates are supplied with 1/2, 1 or 2 ounce electrodeposited copper or reverse treat copper on both sides. Other copper weights and rolled copper foil are available. RS300 is available bonded to a heavy metal ground plane. Aluminum, brass or copper plates also provide an integral heat sink and mechanical support to the substrate.

When ordering for design purposes it is important to note that both thicknesses and dielectric constant of RS300 vary with nominal thickness. The following are optimal values to use for design products please specify thickness, cladding, panel size and any other special considerations. Available master sheet sizes include 36" x 48", and 54" x 48". Typical panel sizes include (but, are not limited to): 18"x 12" and 18"x 24".

RS300

For design purpose it is important to note that both thicknesses and dielectric constant of RS300 vary with nominal thickness. The following are optimal values to use for design:

| Thickness Specification (inch) | 0.0051 ±0.0005 | 0.0094 ±0.0007 | 0.020 ±0.001 | 0.025 ±0.001 | 0.030 ±0.001 | 0.040 ±0.002 | 0.045 ±0.002 | 0.059 ±0.002 | 0.060 ±0.002 |
|---|-------------------|-------------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|
| Thickness Mean (inch) | 0.0051 | 0.0094 | 0.020 | 0.025 | 0.030 | 0.040 | 0.045 | 0.059 | 0.060 |
| Dielectric Constant Specification (10GHz) | 2.79 ±0.03 | 2.89 ±0.03 | 2.92 ±0.03 | 2.94 ±0.03 | 2.94 ±0.03 | 2.94 ±0.03 | 2.94 ±0.03 | 2.94 ±0.03 | 2.94 ±0.03 |

*Thicker Options are available. Please Contact Customer Service or sales of Relong.

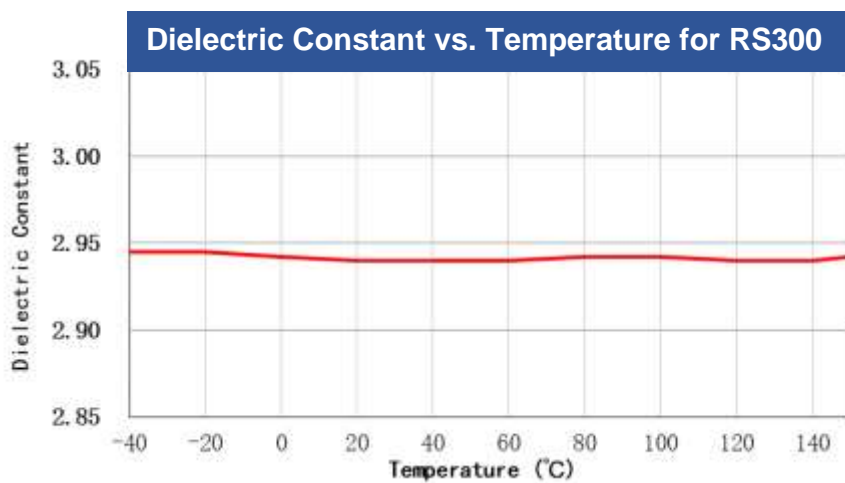


Figure 3

DK/TEMPERATURE CURVE shows the unique thermal stability properties of RS300 materials when thermal cycled over temperature. Even over a wider temperature variation (-40-150°C), the material retains its ultra-stable dielectric constant characteristics. This feature is critical to phase sensitive devices, and phase fed apertures that must perform over a wide temperature range.

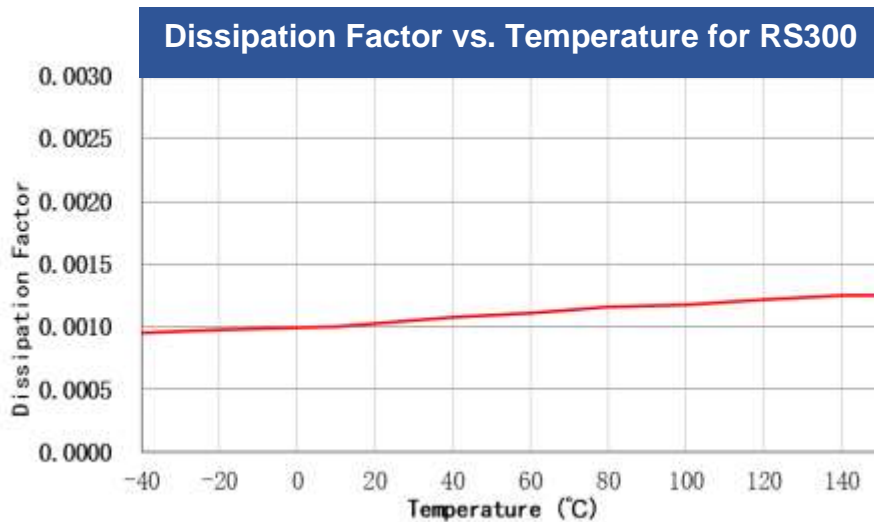


Figure 4

THIS DF/TEMPERATURE CURVE shows the unique thermal stability properties of RS300 materials when thermal cycled over temperature.